



Material Content Data Sheet



Sales Product Name	TLE8366E V33			Issued	28. August 2013			
MA#	MA000971502							
Package	PG-DSO-8-27			Weight*	84.54 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.728	3.23	3.23	32269	32269
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.728	0.86		8608	
wire	non noble metal	copper	7440-50-8	29.548	34.95	35.86	349522	358668
	noble metal	gold	7440-57-5	0.533	0.63	0.63	6300	6300
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1152
plastics	plastics	epoxy resin	-	4.479	5.30		52979	
	inorganic material	silicondioxide	60676-86-0	44.106	52.17	57.59	521734	575865
leadfinish	non noble metal	tin	7440-31-5	0.695	0.82	0.82	8223	8223
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8570	8570
glue	plastics	epoxy resin	-	0.214	0.25		2526	
	noble metal	silver	7440-22-4	0.641	0.76	1.01	7579	10105
*deviation	< 10%			Sum in total:		100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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